

L Number	Hits	Search Text	DB	Time stamp
1	328552	semiconductor or "integrated circuit"	USPAT; US-PGPUB	2002/05/09 14:46
2	538840	adhesive or encapsulant or resin	USPAT; US-PGPUB	2002/05/09 14:46
3	88893	void or voids	USPAT; US-PGPUB	2002/05/09 14:47
4	6378	(adhesive or encapsulant or resin ) with (void or voids )	USPAT; US-PGPUB	2002/05/09 15:10
5	1117	((semiconductor or "integrated circuit" ) and ((adhesive or encapsulant or resin ) with (void or voids ))	USPAT; US-PGPUB	2002/05/09 15:10
6	1320828	pressure or vacuum	USPAT; US-PGPUB	2002/05/09 15:10
7	881	((adhesive or encapsulant or resin ) with (void or voids )) with (pressure or vacuum )	USPAT; US-PGPUB	2002/05/09 15:11
8	184	((semiconductor or "integrated circuit" ) and ((adhesive or encapsulant or resin ) with (void or voids ))) and (((adhesive or encapsulant or resin ) with (void or voids )) with (pressure or vacuum ))	USPAT; US-PGPUB	2002/05/09 15:11
9	78	(((semiconductor or "integrated circuit" ) and ((adhesive or encapsulant or resin ) with (void or voids ))) and (((adhesive or encapsulant or resin ) with (void or voids )) with (pressure or vacuum ))) not (mold or molding)	USPAT; US-PGPUB	2002/05/09 15:12
-	328552	semiconductor or "integrated circuit"	USPAT; US-PGPUB	2002/05/09 14:45
-	538840	adhesive or encapsulant or resin	USPAT; US-PGPUB	2002/05/09 14:46
-	88893	void or voids	USPAT; US-PGPUB	2002/05/09 14:46
-	1036167	heat or heating or heated	USPAT; US-PGPUB	2002/05/09 14:44

Pat Family in STN

Basic Patent (No,Kind,Date): JP 8111470 A2 960430 <No. of Patents: 001>  
BGA PACKAGE, MOUNTING BOARD AND SEMICONDUCTOR DEVICE COMPOSED THEREOF (English)

Patent Assignee: TOSHIBA MICRO ELECTRONICS; TOKYO SHIBAURA ELECTRIC CO

Author (Inventor): ITO SEIGO; SAEGUSA MASATERU

IPC: \*H01L-023/12;

Derwent WPI Acc No: \*G 96-265834; G 96-265834

Language of Document: Japanese

Patent Family:

Patent No	Kind	Date	Applic No	Kind	Date
JP 8111470	A2	960430	JP 94245238	A	941011 (BASIC)

Priority Data (No,Kind,Date):

JP 94245238 A 941011

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(FILE 'HOME' ENTERED AT 17:52:21 ON 09 MAY 2002)

FILE 'INSPEC' ENTERED AT 17:52:30 ON 09 MAY 2002  
E PACKAGING+ALL/CT

L1	1458 E18
L2	20731 VOIDS OR VOID
L3	12 L1 AND L2
L4	13771 RESIN OR ENCAPSULANT
L5	368759 PRESSURE OR VACUUM
L6	5 L1 AND L4 AND L5